1-1. If the aspect ratio of an enhancement n-channel MOSFET is 4 μ m/1 μ m, (the relative model parameters can be seen in Table 1.1) the voltages of drain, gate, source and bulk are 3V, 2V, 0V and 0V respectively, calculate the drain current in this device. Then given the result of another p-channel MOSFET, whose voltages of drain, gate, source, and bulk are -3V, -2V, 0V and 0V respectively.

Table 1.1

Parameter Symbol	Parameter Description	Typical Parameter Value		
		n-Channel	p-Channel	Units
$V_{\scriptscriptstyle{ m T0}}$	Threshold voltage $(V_{BS}=0)$	0.7	-0.7	V
<i>K</i> '	Transconductance parameter (in saturation)	110.0	50.0	$\mu A/V^2$
γ	Bulk threshold parameter	0.4	0.57	V ^{1/2}
λ	Channel length modulation parameter	0.04 (L=1μm) 0.01 (L=2μm)	0.05 (L=1μm) 0.01 (L=2μm)	V ⁻¹
$2 \Phi_{_{\mathrm{F}}} $	Surface potential at strong inversion	0.7	0.8	V

Solution:

NMOS: As $V_D=3V$, $V_G=2V$, $V_S=0V$, $V_B=0V$ So $V_{DS}=3V$, $V_{GS}=2V$, $V_{SB}=0V$

$$V_{THN} = V_{TH0} + \gamma (\sqrt{|2\phi_F + V_{SB}|} - \sqrt{|2\phi_F|}) = 0.7 \text{V}$$

 $\therefore V_{DS} \ge V_{GS} - V_T$, the NMOS works in saturation region and have

$$I_D = \frac{1}{2} K_N \frac{W}{L} (V_{GS} - V_{THN})^2 (1 + \lambda_N V_{DS})$$
$$= \frac{1}{2} \times 110 \times \frac{4}{1} \times (2 - 0.7)^2 (1 + 0.04 \times 3) = 416.4 \mu A$$

PMOS: As V_D =-3V, V_G =-2V, V_S =0V, V_B =0V So V_{SD} =3V, V_{SG} =2V, V_{SB} =0V $V_{THP} = V_{TH0} + \gamma (\sqrt{|2\phi_F + V_{SB}|} - \sqrt{|2\phi_F|})$ =-0.7V

 $\therefore V_{SD} \geq V_{SG} + V_{T_0}$, the PMOS works in saturation region and have

$$I_D = \frac{1}{2} K_P \frac{W}{L} (V_{SG} - |V_{THP}|)^2 (1 + \lambda_P V_{SD})$$

$$= \frac{1}{2} \times 50 \times \frac{4}{1} \times (2 - 0.7)^2 (1 + 0.05 \times 3) = 194.35 \mu A$$

1-2. Find the small-signal model (g_m , g_{mb} , g_{ds}) for an n-channel transistor with the drain at 4 V, gate at 4 V, source at 2 V, and the bulk at 0 V. Assume the model parameters from Table 1.1, and W/L = $10 \ \mu m/1 \ \mu m$.

Solution:

$$\begin{split} V_T &= V_{T0} + \gamma [\sqrt{2\left|\Phi_F\right|} + v_{SB} - \sqrt{2\left|\Phi_F\right|}] \\ V_T &= 0.7 + 0.4[\sqrt{0.7 + 2.0} - \sqrt{0.7}] = 1.02 \\ I_D &= \frac{K'W}{2L} (v_{GS} - v_T)^2 (1 + \lambda v_{DS}) \\ I_D &= \frac{110 \times 10^{-6} \times 10}{2} (2 - 1.02)^2 (1 + 0.4 \times 2) = 570 \times 10^{-6} \\ g_m &= \sqrt{2\frac{K'W}{L}} I_D \\ g_m &= \sqrt{2 \times 110 \times 10^{-6} \times 10 \times 570 \times 10^{-6}} = 1.16 \times 10^{-3} \\ g_{mb} &= g_m \frac{\gamma}{2(2\left|\Phi_F\right| + V_{SB})^{1/2}} \\ g_{mb} &= 1.12 \times 10^{-3} \frac{0.4}{2(0.7 + 2.0)^{1/2}} = 136 \times 10^{-6} \\ g_{ds} &= \lambda I_D \\ g_{ds} &= 570 \times 10^{-6} \times 0.04 = 22.8 \times 10^{-6} \end{split}$$

- 1-3. Current I_{ds} in a transistor is 62.5 μ A when its gate-source voltage is 1V. The current is 1mA when V=2.5V.
- a) Which operating region (linear or saturated) of the transistor is these values of *V* correspond to?
- b) Calculate β and V_T for given transistor.

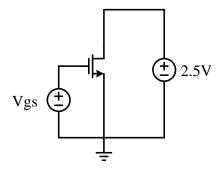


Figure 1.3

Solution:

a) Both V_1 and V_2 are larger than V_T and

$$1 - V_T \le 2.5$$
$$2.5 - V_T \le 2.5$$

Therefore, the transistor works in saturated region in both circumstances.

b) Since

$$\frac{1}{2}\beta_N(1-V_T)^2 = 62.5 \times 10^{-6}$$
$$\frac{1}{2}\beta_N(2.5-V_T)^2 = 1 \times 10^{-3}$$

It can be derived from above equations that

$$V_T = 0.5V$$
$$\beta_N = 500 \mu A/V^2$$

1-4. Show that two MOS transistors connected in parallel with channel widths of W_1 and W_2 and identical channel lengths of L can be modeled as one equivalent MOS transistor whose width is W_1+W_2 and whose length is L, as shown in Fig.1.4. Assume the transistors are identical except for their channel widths.

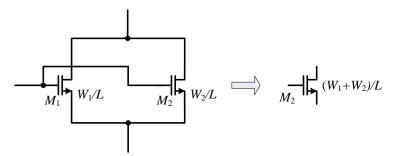


Figure 1.4

Demonstration:

For
$$V_{DS} \leq V_{GS} - V_{TH}$$

$$I_{D1} = \mu C_{OX} \frac{W_1}{L} [(V_{GS} - V_{TH})V_{DS} - \frac{1}{2}V_{DS}^2]$$

$$I_{D2} = \mu C_{OX} \frac{W_2}{L} [(V_{GS} - V_{TH})V_{DS} - \frac{1}{2}V_{DS}^2]$$
.....
$$I_{Dn} = \mu C_{OX} \frac{W_n}{L} [(V_{GS} - V_{TH})V_{DS} - \frac{1}{2}V_{DS}^2]$$

$$\therefore I_D = I_{D1} + I_{D2} + \dots + I_{Dn} = \mu C_{OX} \frac{W_1 + W_2 + \dots + W_n}{L} [(V_{GS} - V_{TH})V_{DS} - \frac{1}{2}V_{DS}^2]$$
For $V_{DS} \geq V_{GS} - V_{TH}$

$$I_D = I_{D1} + I_{D2} + \dots + I_{Dn} = \frac{1}{2} \mu C_{OX} \frac{W_1 + W_2 + \dots + W_n}{L} (V_{GS} - V_{TH})^2$$

Thus the equivalent length = L and the equivalent width = $W_1 + W_2 + ... + W_n$.

1-5. Show that two MOS transistors connected in series with channel lengths of L_1 and L_2 and identical channel widths of W can be modeled as one equivalent MOS transistor whose width is W and whose length is L_1+L_2 , as shown in Fig. 1.5. Assume the transistors are identical except

for their channel lengths. Ignore the body effect and channel-length modulation.

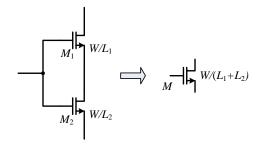
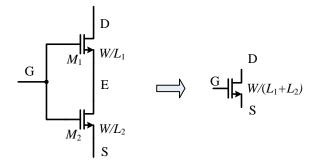


Figure 1.5

Answer:



- (1) When $V_{GS} < V_{TH}$ and $V_{GE} < V_{GS} < V_{TH}$, the MOSFETs are in cut off.
- (2) While M1 operates in triode ($V_{\rm DE} < V_{\rm GE} V_{\rm THN}$), that is equivalent to $V_{\rm DE} + V_{\rm ES} < V_{\rm GE} + V_{\rm ES} V_{\rm THN}$, i.e. $V_{\rm DS} < V_{\rm GS} V_{\rm THN}$.

Thus M2 operates in triode, too.

Thus

$$I_{D1} = \mu_n C_{OX} \frac{W}{L_1} [(V_{GE} - V_{TH}) V_{DE} - \frac{1}{2} V_{DE}^2]$$
 (1)

$$I_{D2} = \mu_n C_{OX} \frac{W}{L_2} [(V_{GS} - V_{TH}) V_{ES} - \frac{1}{2} V_{ES}^2]$$
 (2)

Since

$$V_{DS} = V_{DE} + V \quad (3)$$

$$V_{GE} = V_{GS} V \quad (4)$$

$$I_{D1} = I_{D2} = I_D$$
 (5)

It can be derived from equations (1), (2), (3), (4) and (5) that

$$(V_{GS} - V_{TH})V_{ES} - \frac{1}{2}V_{ES}^{2} = \frac{L_{2}}{L_{1}}[(V_{GS} - V_{TH} - V_{ES})(V_{DS} - V_{ES}) - \frac{1}{2}(V_{DS} - V_{ES})^{2}]$$

$$= \frac{L_{1}}{L_{1} + L_{2}}[(V_{GS} - V_{TH})V_{DS} - \frac{1}{2}V_{DS}^{2}]$$

So we can get
$$I_D = \mu_n C_{OX} \frac{W}{L_1 + L_2} [(V_{GS} - V_{TH})V_{DS} - \frac{1}{2}V_{DS}^2]$$

(3) While M1 operates in saturation ($V_{DE} > V_{GE} - V_{THN}$). It means $V_{DE} + V_{ES} > V_{GE} + V_{ES} - V_{THN}$, i.e. $V_{DS} > V_{GS} - V_{THN}$. $V_E = V_G - V_{GE} < V_G - V_{THN}$, it means $V_{ES} < V_{GS} - V_{THN}$. M2 operates in triode.

So

$$I_{D1} = \frac{1}{2} \mu_n C_{OX} \frac{W}{L_1} (V_{GE} - V_{TH})^2$$
 (1)

$$I_{D2} = \frac{1}{2} \mu_n C_{OX} \frac{W}{L_2} [2(V_{GS} - V_{TH})V_{ES} - V_{ES}^2]$$
 (2)

$$V_{DS} = V_{DE} + V \quad (3)$$

$$V_{GE} = V_{GS} V \quad (4)$$

$$I_{D1} = I_{D2} = I_D$$
 (5)

It can be derived from equations (1), (2), (3), (4) and (5) that

$$I_D = \frac{1}{2} \,\mu_n C_{OX} \, \frac{W}{L_1 + L_2} (V_{GS} - V_{TH})^2$$

That just like a MOSFET operating in saturation, which has a length of L_1+L_2 and a width of W. It can be deducted similarly that n MOSFETs in series acts as a MOSFET with an aspect ratio of $W/(L_1+L_2+\ldots L_n)$.

1-6.A) Fig. 1.6 shows the real and ideal I-V characteristics of two enhancement N-MOSFETs by real line and broken line respectively. Compare the difference of the two MOSFETs and explain why different.

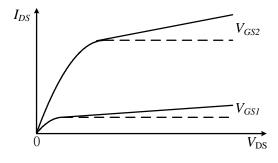


Figure 1.6

B) In Table 1.1, why is γ_P greater than γ_N for a n-well, CMOS technology? Solution:

A) Consider channel length modulation effect:

V_{GS1}——long channel device

V_{GS2}——Short channel device

B) The expression for γ is:

$$\gamma = \frac{\sqrt{2\varepsilon_{si}qN_{SUB}}}{C_{ox}}$$

Because γ is a function of substrate doping, a higher doping results in a larger value for γ . In general, for an nwell process, the well has a greater doping concentration than the substrate and therefore devices in the well will have a larger γ . That's why γ_P is greater than γ_N .

1.7. Given

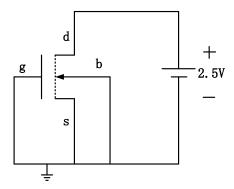


Fig. 1.7

- A) What type (NMOS or PMOS) is transistor shown in Fig. 1.7?
- B) Calculate I_{ds} when this transistor has the same β as the transistor in exercise 1-1 and V_T =-2V.

Solution:

- A) From its polarity of power supply of V_{ds} it can be seen that the transistor is an n-channel MOS transistor.
- B) From V_{gs} it can be seen that the transistor is a depletion transistor.

(由于题干没有说明, 计不计入沟长调制效应都算对)